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Dated: October 5, 2005

Signature:

Richard H. Anderson
(Richard H. Anderson)

Docket No.: 28569/38510
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Mingming Fang et al.

Application No.: 10/677,433

Confirmation No.: 9007

Filed: October 2, 2003

Art Unit: 1765

For: CHEMICAL-MECHANICAL POLISHING
(CMP) SLURRY AND METHOD OF
PLANARIZING SURFACES

Examiner: P. A. George

AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

In response to the Office Action dated July 5, 2004, please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 3 of this paper.